Innovators in Socket Technology

We provide proven solutions to our customers, worldwide.

Boyd delivered more than 8 million memory sockets in 2004.

The Interconnection team works on next generation sockets to meet the newest requirements of our customers’ rapidly growing markets.
Product Roadmap

Future is clear - More I/O at smaller sizes

- Using the latest 3D design tools such as SolidWorks and non-linear FEA, the Interconnection engineers create new designs to meet your schedule.

- The availability of on-site model shops and rapid prototyping facilities allows the creation of prototypes so customers can evaluate new designs and concepts in days instead of weeks.

- A comprehensive technical service laboratory with advanced thermal analysis capabilities and wind tunnels allows Sensata to evaluate the thermal characteristics of the sockets.

Moore’s Law continues to be validated as semiconductor companies drive more function in smaller form factors. The back-end packaging and assembly teams support this drive with the development of new package formats for SIP, stacked die and stacked packages. Suppliers of burn-in sockets are challenged to develop sockets for these new packages with higher I/O. Boyd Interconnection team eliminates the burn-in socket selection process by partnering with our customers to understand their needs and provide the optimal solution.

Product Features

Three primary contact designs have been developed to satisfy customer requirements for reliable electrical and mechanical interconnect. These contacts leave small “witness marks” on the solder ball and are available for Pb/Sn and Pb-free solder balls. The contacts, which open to allow package insertion, touch the solder ball above the equator when closed.

- Various contact designs
- Lower resistance contacts
- Customized plating options

Witness mark left by Boyd contact
Delivering World Class Solutions

Providing customers with solutions, Boyd Interconnection creates burn-in sockets for the semiconductor electronics industry to ensure the quality and reliability of the packaged device. Boyd engineers work with customers to provide a burn-in socket which maximizes the customers’ burn-in system capacity for the lowest overall cost of ownership. Boyd offers a portfolio of sockets to serve memory manufacturers.

Design Features

- Open-top, auto-load actuated socket
- Small socket outline maximizes burn-in board density and process throughput
- Multiple package outlines and heights
- Custom options: adapter-less, coverless, lead lengths, plating options, color options

BGA Memory Socket Platforms (Series)

Memory Portfolio

- Extensive product offering
- Numerous pitches available
- Socket outlines maximize board density

Socket Attributes

- Proven contact
- Small socket outline
- Numerous socket platforms
- Removable adapter

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